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DATASHEET

SMD • Low Power LED 45-21/XK2C-BXXXXXXXXXX/2T



Features

- · PLCC-2 package
- · Top view white LED
- High luminous intensity output
- Wide viewing angle
- Pb-free
- · RoHS compliant

Description

The Everlight 45-21 package has high efficacy, high CRI, low power consumption, wide viewing angle and a compact form factor. These features make this package an ideal LED for all lighting applications.

Applications

- · General lighting
- · Decorative and Entertainment Lighting
- Indicators
- Illumination
- · Switch lights



Product Number Explanation

45-21 / X K 2 C - B XX XX XX XX XX / 2T

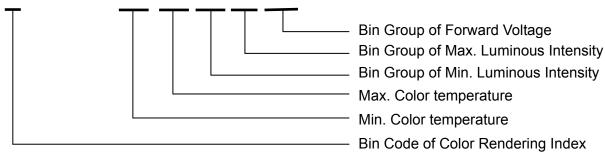


Table of Color Rendering Index

Symbol	Description
M	CRI(Min.): 60
N	CRI(Min.): 65
L	CRI(Min.): 70
Q	CRI(Min.): 75
K	CRI(Min.): 80
Н	CRI(Min.): 90

Note:

Tolerance of Color Rendering Index: ±2

Example:

45-21/LK2C-B4556AC2CB2/2T

CRI	70(Min.)
ССТ	4500K~5650K
lv	1800mcd~2200mcd
VF	2.9V~3.6V
I _F	20mA



Mass Production list

Product	CRI Min.	сст(к)	lv (mcd) Min.	lv(mcd) Typ.	lv(mcd) Max.	Ф(lm) Тур.
45-21/LK2C-B56702C4CB2/2T	70	5650K~7000K	2000	2200	2400	6.8
45-21/LK2C-B50634C6CB2/2T	70	5000K~6300K	2200	2400	2600	7.4
45-21/LK2C-B45562C4CB2/2T	70	4500K~5650K	2000	2200	2400	6.8
45-21/LK2C-B38452C4CB2/2T	70	3800K~4500K	2000	2200	2400	6.8
45-21/LK2C-B2832AC2CB2/2T	70	2850K~3250K	1800	2000	2200	6.2

Mass Production list

Product	CRI Min.	сст(к)	lv (mcd) Min.	lv(mcd) Typ.	lv(mcd) Max.	Ф(lm) Тур.
45-21/QK2C-B56702C4CB2/2T	75	5650K~7000K	2000	2200	2400	6.8
45-21/QK2C-B50632C4CB2/2T	75	5000K~6300K	2000	2200	2400	6.8
45-21/QK2C-B45562C4CB2/2T	75	4500K~5650K	2000	2200	2400	6.8
45-21/QK2C-B3845AC2CB2/2T	75	3800K~4500K	1800	2000	2200	6.2
45-21/QK2C-B2832AC2CB2/2T	75	2850K~3250K	1800	2000	2200	6.2

Note:

- 1. Tolerance of Luminous flux: ±11%.
- 2. Lm (Typ.) value just for reference.



Device Selection Guide

Chip Materials	Emitted Color	Resin Color
	Cool White	
InGaN	Neutral White	Water Clear
	Warm White	

Absolute Maximum Ratings ($T_{Soldering}=25^{\circ}C$)

Parameter	Symbol	Rating	Unit	
Forward Current	I _F	30	mA	
Peak Forward Current (Duty 1/10 @10ms)	I _{FP}	100	mA	
Power Dissipation	P _d	110	mW	
Operating Temperature	T _{opr}	-40 ~ +85	°C	
Storage Temperature	T _{stg}	-40 ~ +100	°C	
Thermal Resistance (Junction / Soldering point)	R _{th J-S}	75	°C/W	
Junction Temperature	T _j	125	°C	
Soldering Temperature	T_{sol}	Reflow Soldering : 260 °C for 10 sec.		
		Hand Soldering: 350 °C for 3 sec.		

Note:

The products are sensitive to static electricity and must be carefully taken when handling products

Electro-Optical Characteristics (T_{Soldering}=25°C)

Parameter	Symbol	Min.	Тур.	Max.	Unit	Condition
Luminous intensity	Iv	1800		2600	mcd	I _F =20mA
Forward Voltage	V_{F}	2.9		3.6	V	I _F =20mA
Viewing Angle	2θ _{1/2}		120		deg	I _F =20mA

Notes

- 1. Tolerance of Luminous flux: ±11%.
- 2. Tolerance of Forward Voltage: ±0.1V.



Bin Range of Luminous intensity

Bin Code	Min.	Max.	Unit	Condition
AC	1800	2000		
2C	2000	2200	- mad	1 =20m A
4C	2200	2400	mcd	I _F =20mA
6C	2400	2600	_	

Note:

Tolerance of Luminous Intensity: ±11%

Bin Range of Forward Voltage

Group	Bin Code	Min.	Max.	Unit	Condition
	36	2.9	3.0		
	37	3.0	3.1	_	
	38	3.1	3.2		
B2	39	3.2	3.3	V	I _F =20mA
	40	3.3	3.4		•
	41	3.4	3.5		
	42	3.5	3.6	_	

Note:

Tolerance of Forward Voltage: ±0.1V.



Bin Range of Chromaticity Coordinates

ССТ	Bin Code	CIE_x	CIE_y	сст	Bin Code	CIE_x	CIE_y
		0.3031	0.3327			0.3288	0.3569
	X5	0.3148	0.3444		V5	0.3469	0.3717
	YO	0.3160	0.3332		Vo	0.3458	0.3592
7000K		0.3052	0.3224	5650K		0.3290	0.3451
~6300K		0.3052	0.3224	~5000K		0.3290	0.3451
	X6	0.3160	0.3332		V6	0.3458	0.3592
	Λ0	0.3175	0.3204			0.3444	0.3442
		0.3076	0.3108			0.3292	0.3313
		0.3148	0.3444		U5	0.3469	0.3717
	\A/5	0.3288	0.3569			0.3642	0.3829
	W5	0.3290	0.3451			0.3622	0.3716
6300K		0.3160	0.3332	5000K		0.3458	0.3592
~5650K		0.3160	0.3332	~4500K		0.3458	0.3592
	W6	0.3290	0.3451		U6	0.3622	0.3716
	VVO	0.3292	0.3313		Uo	0.3594	0.3557
		0.3175	0.3204			0.3444	0.3442

Note:

The value is based on driving current by 20mA.
Tolerance of Chromaticity Coordinates: ±0.01



Bin Range of Chromaticity Coordinates

сст	Bin Code	CIE_x	CIE_y	сст	Bin Code	CIE_x	CIE_y
		0.3642	0.3829			0.3963	0.4035
	T5	0.3811	0.3937		R5	0.4148	0.4161
	15	0.3783	0.3825		K5	0.4086	0.3995
4500K		0.3622	0.3716	3800K		0.3924	0.3909
~4100K		0.3622	0.3716	~3500K		0.3924	0.3909
	Т6	0.3783	0.3825		R6	0.4086	0.3995
	10	0.3741	0.3658		K0	0.4021	0.3822
		0.3594	0.3557			0.3871	0.3739
		0.3811	0.3937		0.5	0.4148	0.4161
	O.F.	0.3963	0.4035	3500K ~3250K		0.4312	0.4234
	S5	0.3924	0.3909		Q5	0.4240	0.4065
4100K		0.3783	0.3825			0.4086	0.3995
~3800K		0.3783	0.3825		Q6	0.4086	0.3995
	0.6	0.3924	0.3909			0.4240	0.4065
	S6	0.3871	0.3739		Qo	0.4165	0.3890
		0.3741	0.3658			0.4021	0.3822
		0.4312	0.4234			0.4456	0.4287
	P5	0.4456	0.4287		N5	0.4614	0.4333
	P5	0.4376	0.4116		CNI	0.4525	0.4162
3250K		0.4240	0.4065	3050K		0.4376	0.4116
~3050K		0.4240	0.4065	~2850K		0.4376	0.4116
	De	0.4376	0.4116		Ne	0.4525	0.4162
	P6	0.4294	0.3943		N6	0.4436	0.3991
		0.4165	0.3890			0.4294	0.3943

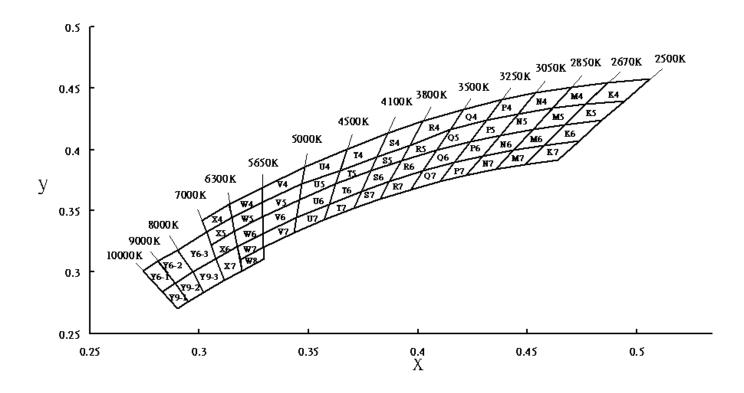
Note

^{1.} The value is based on driving current by 20mA.

^{2.} Tolerance of Chromaticity Coordinates: ±0.01

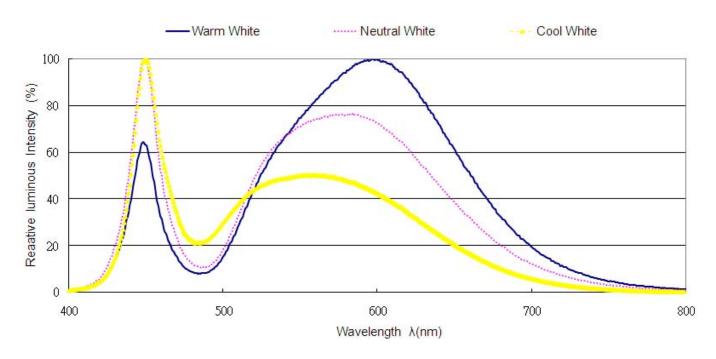


The C.I.E. 1931 Chromaticity Diagram





Spectrum Distribution



Typical Electro-Optical Characteristics Curves

Fig.1 - Forward Voltage Shift vs.

Junction Temperature

0.20 > 0.15 0.10 0.05 0.00 0.05 0.00 -0.05 -0.10 -0.15 -0.20 -50 -25 0 25 50 75 100 Tj - Junction Temperature (°C)

Fig.2 - Relative Luminous Intensity

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Typical Electro-Optical Characteristics Curves

Fig.3 - Relative Luminous Intensity vs. Junction Temperature

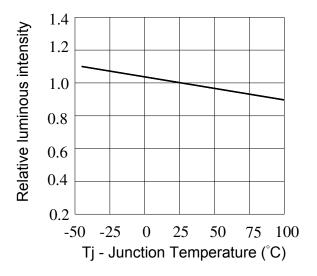


Fig.5 - Max. Driving Forward Current vs.Soldering Temperature

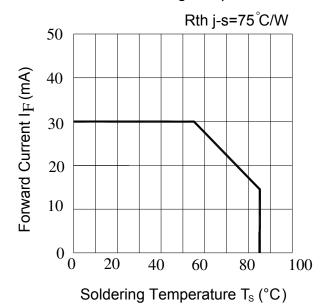


Fig.4 - Forward Current vs. Forward Voltage

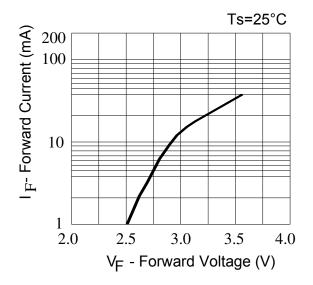
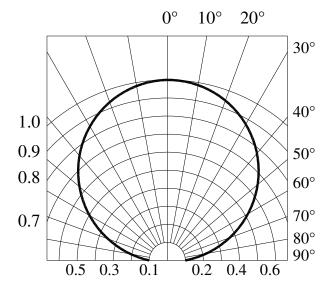
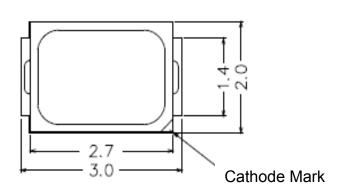


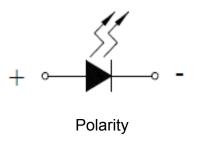
Fig.6 - Radiation Diagram

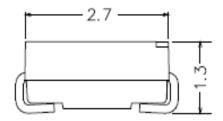


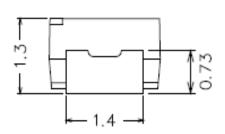


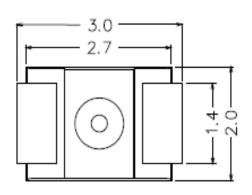
Package Dimension

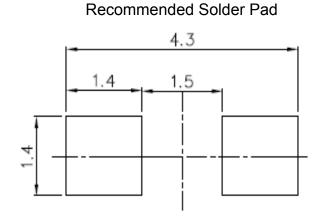












Note:

Tolerance unless mentioned is ±0.2mm; Unit = mm



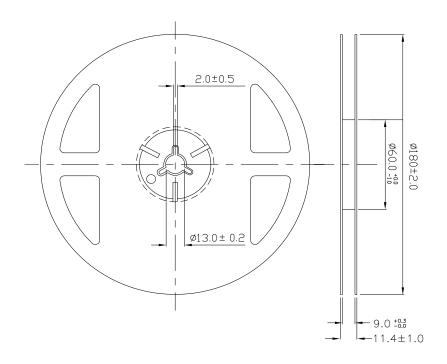
Moisture Resistant Packing Materials

Label Explanation



- CPN: Customer's Product Number
- P/N: Product Number
- · QTY: Packing Quantity
- · CAT: Luminous Intensity Rank
- · HUE: Dom. Wavelength Rank
- REF: Forward Voltage Rank
- · LOT No: Lot Number

Reel Dimensions

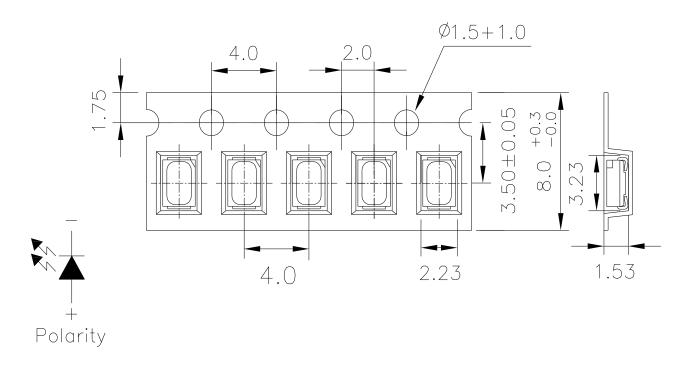


Note:

Tolerances unless mentioned ± 0.1 mm. Unit = mm



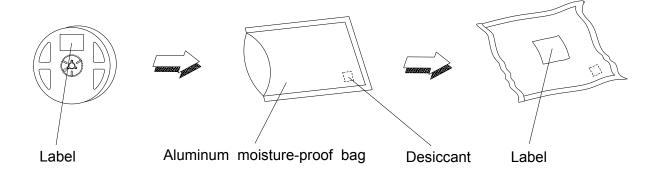
Carrier Tape Dimensions: Loaded Quantity 2000 pcs Per Reel



Note:

Tolerances unless mentioned ±0.1mm. Unit = mm

Moisture Resistant Packing Process





Reliability Test Items and Conditions

The reliability of products shall be satisfied with items listed below.

Confidence level: 90%

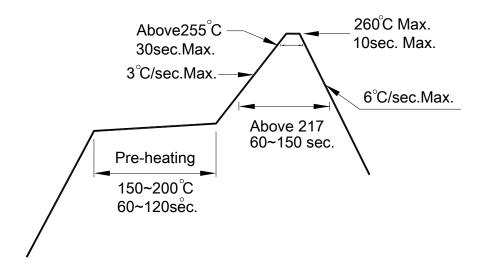
LTPD: 10%

No.	Items	Test Condition	Test Hours/Cycles	Sample Size	Ac/Re
1	Reflow Soldering	Temp.: 260°C/10sec.	6 Min.	22 PCS.	0/1
2	Thermal Shock	H : +100°C 5min ∫ 10 sec L : -10°C 5min	200 Cycles	22 PCS.	0/1
3	Temperature Cycle	H : +100°C 15min ∫ 5 min L : -40°C 15min	200 Cycles	22 PCS.	0/1
4	High Temperature/Humidity Reverse Bias	Ta=85°C,85%RH	1000 Hrs.	22 PCS.	0/1
5	High Temperature/Humidity Operation	Ta=85°C,85%RH, I _F = 20 mA	1000 Hrs.	22 PCS.	0/1
6	Low Temperature Storage	Ta=-40°C	1000 Hrs.	22 PCS.	0/1
7	High Temperature Storage	Ta=85°C	1000 Hrs.	22 PCS.	0/1
8	Low Temperature Operation Life	Ta=-40°C, I _F = 30 mA	1000 Hrs.	22 PCS.	0/1
9	High Temperature Operation/ Life#1	Ta=25°C, I _F = 30 mA	1000 Hrs.	22 PCS.	0/1
10	High Temperature Operation/ Life#2	Ta=55°C, I _F =30 mA	1000 Hrs.	22 PCS.	0/1
11	High Temperature Operation/ Life#3	Ta=85°C, I _F = 20 mA	1000 Hrs.	22 PCS.	0/1



Precautions for Use

- 1. Over-current-proof
 - Customer must apply resistors for protection; otherwise slight voltage shift will cause big current change (Burn out will happen).
- 2. Storage
 - 2.1 Do not open moisture proof bag before the products are ready to use.
 - 2.2 Before opening the package: The LEDs should be kept at 30°C or less and 90%RH or less.
 - 2.3 After opening the package: The LED's floor life is 168 Hrs under 30°C or less and 60% RH or less. If unused LEDs remain, it should be stored in moisture proof packages.
 - 2.4 If the moisture absorbent material (silica gel) has faded away or the LEDs have exceeded the storage time, baking treatment should be performed using the following conditions.
 - Baking treatment: 60±5°C for 24 hours.
- 3. Soldering Condition
 - 3.1 Pb-free solder temperature profile



- 3.2 Reflow soldering should not be done more than two times.
- 3.3 When soldering, do not put stress on the LEDs during heating.
- 3.4 After soldering, do not warp the circuit board.



4. Soldering Iron

Each terminal is to go to the tip of soldering iron temperature less than 350°C for 3 seconds within once in less than the soldering iron capacity 25W. Leave two seconds and more intervals, and do soldering of each terminal. Be careful because the damage of the product is often started at the time of the hand solder.

5. Repairing

Repair should not be done after the LEDs have been soldered. When repairing is unavoidable, a double-head soldering iron should be used (as below figure). It should be confirmed beforehand whether the characteristics of the LEDs will or will not be damaged by repairing.

